



Product Content Sheet

Package family	uCSP	Picture of typical product, optional
Date	26/Oct/2006	
Version	RoHS	

Composition part	Material group	Materials	CAS if applicable	Average mass [weight-%] *)	Sum [%]	Traces
Chip	Silicon and inorganic compounds	Si	7440-21-3	100	10.3577	-
Bump and RDL	Polymer	B-staged divinylsiloxane-bis-benzocyclobutene	124221-30-3	25-44	11.25-19.8	-
		Mesitylene	000108-67-8	50-75	22.5-33.75	-
		2,6-bis((4-azidophenyl)methylene)-4-ethylcyclohexanone	114391-97-8	0.3-2.7	0.135-1.215	-
	Metal alloy	Al	7429-90-5	99.999	3.333	-
		Ni	7440-02-0	99.95	1.665	-
		V	7440-62-2	99.95	1.665	-
		Cu	7440-50-8	99.99	3.333	-
	Solder alloy	Ag	7440-22-4	99.9	0.3605	-
		Cu	7440-50-8	99.95	0.175	-
		Ni	7440-02-0	99.99	0.357	-
		Sn	7440-31-5	99.99	34.4288	-
Marking	Laser	Laser	-	-	-	-
Sum in total:					100	-

Weight range	0.001 g
Fluctuation margin	25%

or:

Case sizes**) and weight range

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*) related to package weight; weight in particular, see corresponding *package weight list*

**) optional

Not part of package family	
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Company	Texas Instruments Norway	Important remarks: 1) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight. Higher limits are accepted if the substance or material is legally regulated (see note no. 2). 2) A list of the (legal) "... restrictions on substances ..." or materials is available at internet address: http://www.eicta.org/Content/Default.asp?PageID=113 . 3) Substances, materials etc. with possible harmful effects on human beings and the environment are listed.
Address	Gaustadalleen 21, 0349 Oslo, Norway	
Support	http://www-k.ext.ti.com/sc/technical-support/pic/euro.htm	
Internet	www.ti.com	

- 4) There are no risks for human beings and to the environment if products are properly used as designated.
This shall not apply to risks caused during procedures for disposal etc.
- 5) All statements herein are based on our present knowledge.
If our products are used properly, there are no risks to human beings and/or the environment.



Package Weight List

(Single weights of Products, materials data see Product Content Sheet on previous page)

Package family	uCSP
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Uspec short*)	Package family*)	Package	Internal package code	Pin count	Weight [grams]	Remark
		ultraCSP	uCSP	28	0.001 g	Device: CC1000

*) USpec short name and Package family are optional, e.g. for summary of several package weight lists

Company	Texas Instruments Norway
Address	Gaustadalleen 21, 0349 Oslo, Norway
Support	http://www-k.ext.ti.com/sc/technical-support/pic/euro.htm
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